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## **New Chip Scale ReadyMount(TM) EC LED Series From SemiLEDs**

### **Combines SemiLEDs' Flip Chip and ReadyWhite(TM) Technologies for Innovative White-Chip Solution**

CHUNAN, Taiwan, Aug. 26, 2014 (GLOBE NEWSWIRE) -- SemiLEDs Corporation (Nasdaq:LEDS), a global provider of vertical LED technology solutions, today announced sampling and mass production availability of its newest line of white chip scale packages, the ReadyMount™ Enhanced CSP, or EC series. By combining SemiLEDs' Enhanced Flip chip (EF) approach with the company's innovative ReadyWhite™ phosphor technology, the EC delivers unprecedented flexibility, reliability and manufacturability in a single 1.4 x 1.4mm low profile device. Rated for input power of up to 3W, the EC is a fully packaged white emitter SMD component, ready for surface mounting on any board level module or COB application, lowering capital costs and enabling extremely high lumen density configurations.

Mark Tuttle, General Manager for SemiLEDs Optoelectronics Co., Ltd., commented, "The new ReadyMount white chip scale package is leveraging a powerful synergy within SemiLEDs' broad technology portfolio to create an entirely new value point in the LED industry. Our unique Chip Scale Package (CSP) brings all the benefits of SemiLEDs' rugged EF Series FlipChip architecture to an extremely compact emitter, which is simple to integrate using standard tape and reel surface mount manufacturing. This innovation reduces final component cost up to 50%, with a packaging cost reduction of up to 80% over conventional packaging. EC Series products, such as the EC-W1414, enable system-integrators and luminaire manufacturers a direct path to a highly cost effective solution on a per-lumen basis now, with additional viewing angles and die sizes under development."

While useful for creating compact multi-die white packaged LEDs, the ReadyMount products will provide particular benefit to light-engine and luminaire manufacturers who have previously had to rely exclusively upon packaged die solutions. Incorporating SemiLEDs' EF Series FlipChip, the electrical contacts are moved to the bottom of the chip leaving an emitting surface that is uninterrupted by wire bonds or top-side electrodes. The result is a compact chip scale package, only 0.4mm high, which can produce outputs of up to 300 lumens at 1A. The SemiLEDs EC series is available in standard ReadyWhite™ correlated color temperatures ranging from 2700K to 10,000K with color rendering indices up to 90 minimum.

In addition to the manufacturing benefits of the chip scale package, elimination of the wire bonds also improves the optical integration characteristics by taking advantage of the unobstructed and nearly edge-to-edge emitting chip surface which enables the die to be mounted very close together. This simplifies the optics by eliminating the need for complex mixing lenses which are used to control ghosting and shadows in narrow beam applications. The glass top surface is also very mechanically robust, and is not prone to the handling damage or stresses faced by wire-bond or flip chips with a silicone covering. The typical 145 degree field of view also demonstrates good color-over-angle characteristics as a result of the ReadyWhite technology.

By enabling densely packed mounting with simplified optics, the SemiLEDs EC series is ideal for general lighting applications including indoor and outdoor lighting, architectural lighting, and torches/flashlights. The rugged architecture and compact size of the single white die are additionally well suited for mobile device flashes and LCD backlighting applications.

SemiLEDs' CSP series of LED chips is RoHS compliant with production quantities available now.

### **About SemiLEDs Corporation**

SemiLEDs develops and manufactures LED chips and LED components primarily for general lighting applications, including street lights and commercial, industrial and residential lighting, along with specialty industrial applications such as ultraviolet (UV) curing, medical/cosmetic, counterfeit detection, and horticulture. SemiLEDs sells blue, white, green and UV LED chips. For completed product information, please visit [www.semileds.com](http://www.semileds.com), email [sales@semileds.com](mailto:sales@semileds.com), or tel +866 (37) 586-788 (Taiwan).

### **Forward Looking Statements**

This press release contains statements that may constitute "forward-looking" statements within the meaning of Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended, and as defined in the U.S. Private Securities Litigation Reform Act of 1995. All statements other than statements of historical fact could be deemed forward-looking, including, but not limited to, any projections of future revenues, income, margins or other financial information; any statements about historical results that may suggest trends for SemiLEDs' business; any statements of the plans, strategies and objectives of management for future operations; any statements of expectation or belief regarding

recovery of the LED industry, market opportunities and other future events or technology developments; any statements regarding SemiLEDs' position to capitalize on any market opportunities; and any statements of assumptions underlying any of the foregoing. These forward-looking statements are based on current expectations, estimates, forecasts and projections of future SemiLEDs' or industry performance based on management's judgment, beliefs, current trends and market conditions and involve risks and uncertainties that may cause actual results to differ materially from those contained in the forward-looking statements. SemiLEDs' Annual Report on Form 10-K filed with the Securities and Exchange Commission (the "SEC") and other SemiLEDs filings with the SEC (which you may obtain for free at the SEC's website at <http://www.sec.gov>) discuss some of the important risks and other factors that may affect SemiLEDs' business, results of operations and financial condition. SemiLEDs undertakes no intent or obligation to publicly update or revise any of these forward looking statements, whether as a result of new information, future events or otherwise, except as required by law.

ReadyWhite™ and ReadyMount™ are trademarks of SemiLEDs Corporation.

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